

MOS FIELD EFFECT TRANSISTOR

2SK2479

SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

DESCRIPTION

The 2SK2479 is N-Channel MOS Field Effect Transistor designed for high voltage switching applications.

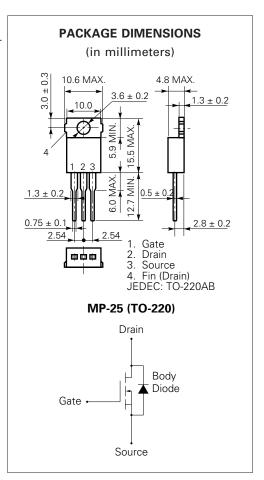
FEATURES

- Low On-Resistance $R_{DS(on)} = 7.5 \Omega \text{ (Vgs} = 10 \text{ V, ID} = 2.0 \text{ A)}$
- Low Ciss Ciss = 485 pF TYP.
- High Avalanche Capability Ratings

ABSOLUTE MAXIMUM RATINGS (TA = 25 °C)

Drain to Source Voltage	V_{DSS}	900	V
Gate to Source Voltage	Vgss	±30	V
Drain Current (DC)	ID(DC)	±3.0	Α
Drain Current (pulse)*	ID(pulse	e) ±8.0	Α
Total Power Dissipation ($T_c = 25$ °C)	P _{T1}	70	W
Total Power Dissipation (T _A = 25 °C)	P _{T2}	1.5	W
Channel Temperature	T_ch	150	°C
Storage Temperature	T_{stg}	-55 to +150	°C
Single Avalanche Current**	las	3.0	Α
Single Avalanche Energy**	Eas	5.4	mJ

- * PW \leq 10 μ s, Duty Cycle \leq 1 %
- ** Starting Tch = 25 °C, Rg = 25 Ω , Vgs = 20 V \rightarrow 0



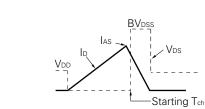


ELECTRICAL CHARACTERISTICS (TA = 25 °C)

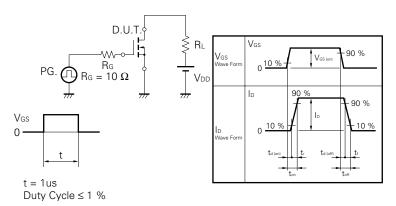
CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Drain to Source On-State Resistance	RDS(on)		5.6	7.5	Ω	Vgs = 10 V, ID = 2.0 A
Gate to Source Cutoff Voltage	V _{GS(off)}	2.5		3.5	V	V _{DS} = 10 V, I _D = 1 mA
Forward Transfer Admittance	l yfs l	8.0			S	V _{DS} = 20 V, I _D = 2.0 A
Drain Leakage Current	IDSS			100	μΑ	V _{DS} = V _{DSS} , V _{GS} = 0
Gate to Source Leakage Current	Igss			±100	nA	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$
Input Capacitance	Ciss		485		pF	V _{DS} = 10 V
Output Capacitance	Coss		75		pF	V _G S = 0
Reverse Transfer Capacitance	Crss		10		pF	f = 1 MHz
Turn-On Delay Time	td(on)		12		ns	ID = 2.0 A
Rise Time	tr		5		ns	V _G S = 10 V
Turn-Off Delay Time	td(off)		35		ns	V _{DD} = 150 V
Fall Time	tf		8		ns	$R_G = 10 \Omega$
Total Gate Charge	QG		17		nC	ID = 3.0 A
Gate to Source Charge	Qgs		3		nC	V _{DD} = 450 V
Gate to Drain Charge	QgD		8		nC	V _G S = 10 V
Body Diode Forward Voltage	V _{F(S-D)}		1.0		V	IF = 3.0 A, VGS = 0
Reverse Recovery Time	trr		670		ns	IF = 3.0 A, VGS = 0
Reverse Recovery Charge	Qrr		3.0		μC	$di/dt = 50 A/\mu s$

Test Circuit 1 Avalanche Capability

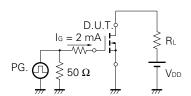
$V_{GS} = 20 - 0 \text{ V}$ $V_{GS} = 20 - 0 \text{ V}$ V_{DD} V_{DD}



Test Circuit 2 Switching Time

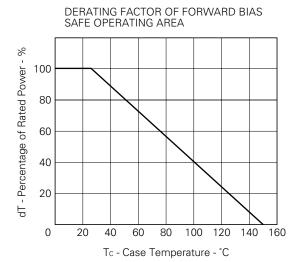


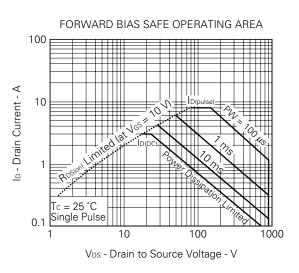
Test Circuit 3 Gate Charge

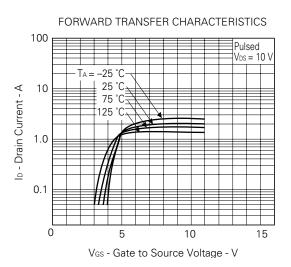


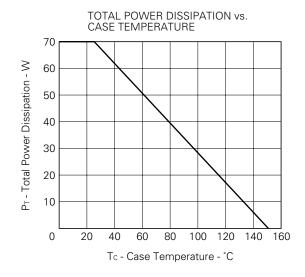
The application circuits and their parameters are for references only and are not intended for use in actual design-in's.

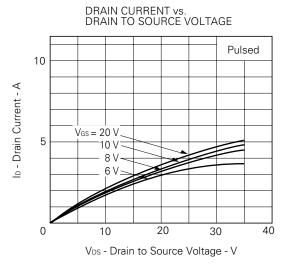
TYPICAL CHARACTERISTICS (TA = 25 °C)



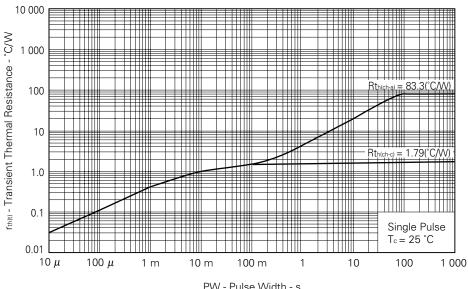






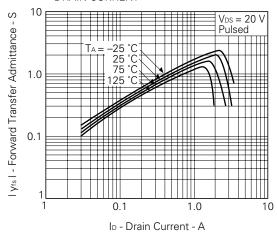


TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

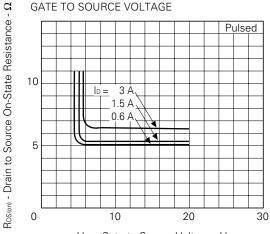


PW - Pulse Width - s



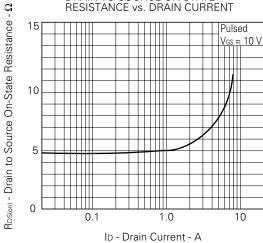


DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

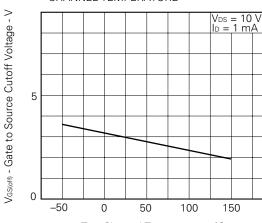


V_{GS} - Gate to Source Voltage - V

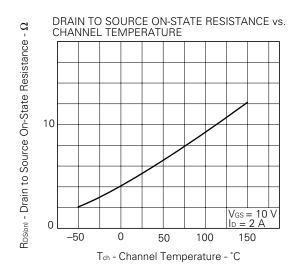
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

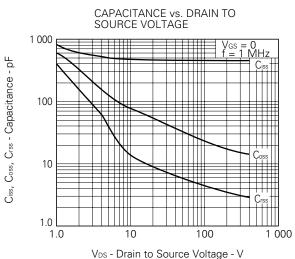


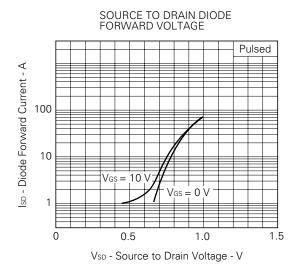
GATE TO SOURCE CUTOFF VOLTAGE vs. CHANNEL TEMPERATURE

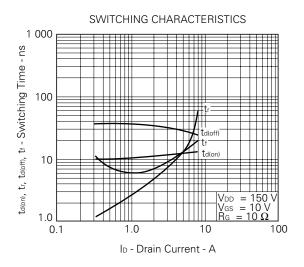


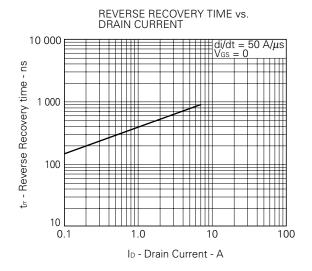
 T_ch - Channel Temperature - $^\circ\mathsf{C}$

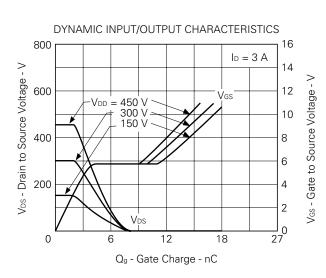




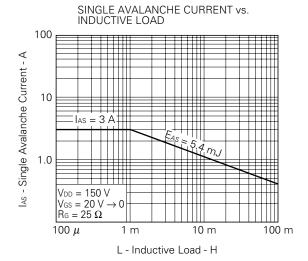


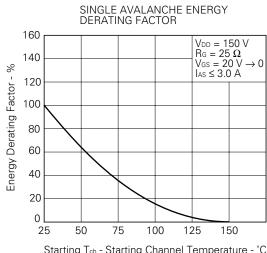














REFERENCE

Document Name	Document No.
NEC semiconductor device reliability/quality control system.	TEI-1202
Quality grade on NEC semiconductor devices.	IEI-1209
Semiconductor device mounting technology manual.	IEI-1207
Semiconductor device package manual.	IEI-1213
Guide to quality assurance for semiconductor devices.	MEI-1202
Semiconductor selection guide.	MF-1134
Power MOS FET features and application switching power supply.	TEA-1034
Application circuits using Power MOS FET.	TEA-1035
Safe operating area of Power MOS FET.	TEA-1037

7

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